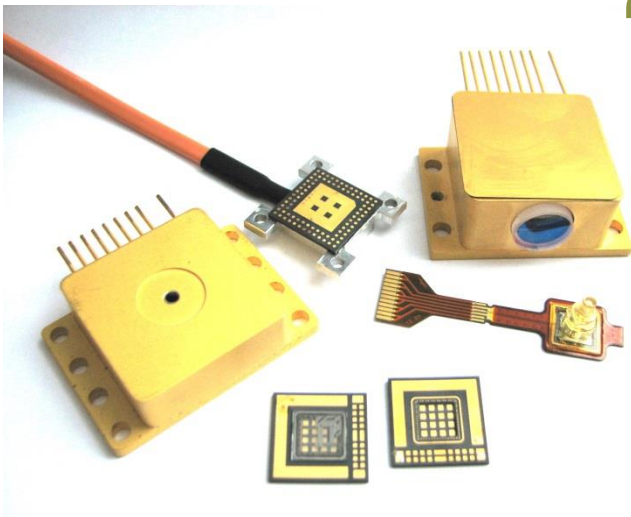


# Packaging

## Customized Components

Based on a strong expertise in product design and assembly process of optoelectronic components and sub-systems, Innoptics offers various packaging services : proof of concept, product design, prototyping, subcontracting of specific assembly steps, manufacturing in small to medium quantities...



“ Innoptics handles a large range of technologies and multiple assembly processes, allowing the choice of the most appropriate solution for any customer need.

From feasibility study to manufacturing, our highly skilled experts in optics, mechanical engineering, thermal management and RF design are familiar with chip on carrier assembly as well as with package design and module assembly. ”

### ► Services

- Feasibility Study
- Design
- Process development
- Prototyping
- Manufacturing
- Sub-contracting
- Consulting

### ► Fields of applications

- Scientific instrumentation
- Communications
- Space and aeronautics
- Medical
- Gas Analysis
- Industry

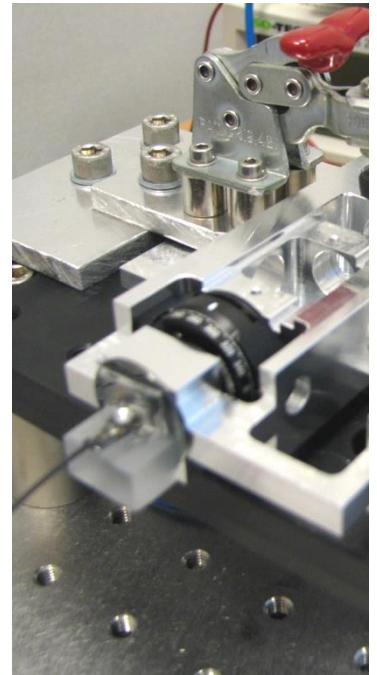
# Know-how

## ► Design & modeling

- Optical, mechanical, thermal and RF design
- Singlemode or multimode coupling
- Free-space transmission

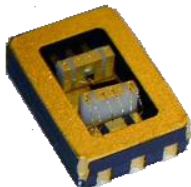
## ► Assembly

- Soldering, gluing, thermocompression bonding ...
- Flip-chip assembly of optoelectronic chips and ICs
- Design of assembly tools and benches
- Wire bonding
- Package integration
- Hermetic sealing



# Product examples

## ► Optocoupler



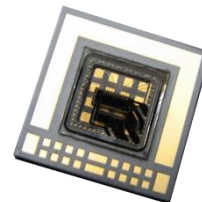
## ► TOSA & ROSA Modules



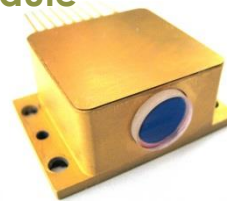
## ► Fiber optic transceiver



## ► Hermetic transceiver



## ► HHL Module



## ► 12x 10Gbps Emitter/Receiver

